

MITSUBISHI RF POWER TRANSISTOR

**2SC3104**

**NPN EPITAXIAL PLANAR TYPE**

**DESCRIPTION**

2SC3104 is a silicon NPN epitaxial planar type transistor specifically designed for UHF power amplifier applications.

**FEATURES**

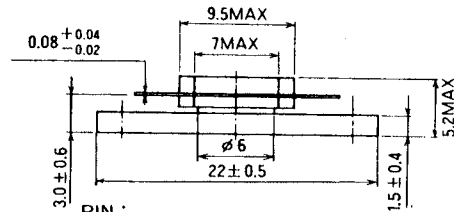
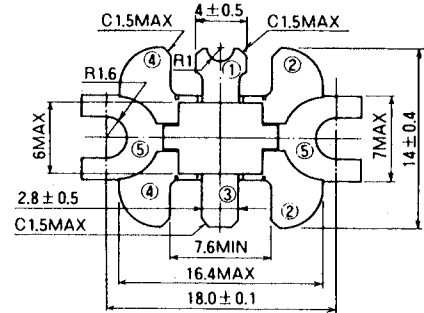
- High power gain:  $G_{pe} \geq 4.7\text{dB}$   
@  $V_{CC} = 7.2\text{V}$ ,  $f = 520\text{MHz}$ ,  $P_{in} = 2\text{W}$ .
- Emitter ballasted construction.
- High ruggedness: Ability to withstand more than 20:1 load VSWR when operated at  $V_{CC} = 9\text{V}$ ,  $f = 520\text{MHz}$ ,  $P_o = 6\text{W}$ .
- Flange type ceramic package.
- $Z_{in} = 1.6 - j0.4 \Omega$ ,  $Z_{out} = 3.5 - j1.0 \Omega$  at  $V_{CC} = 7.2\text{V}$ ,  $f = 520\text{MHz}$ ,  $P_o = 6\text{W}$ .

**APPLICATION**

For output stage of 5W power amplifiers in UHF band portable type radio set.

**OUTLINE DRAWING**

Dimensions in mm



PIN :

- ① COLLECTOR
- ② EMITTER (FLANGE)
- ③ BASE
- ④ EMITTER (FLANGE)
- ⑤ FIN (EMITTER)

**T-31E**

**ABSOLUTE MAXIMUM RATINGS** ( $T_c = 25^\circ\text{C}$ )

Symbol	Parameter	Conditions	Ratings	Unit
$V_{CBO}$	Collector to base voltage		20	V
$V_{EBO}$	Emitter to base voltage		3.5	V
$V_{CEO}$	Collector to emitter voltage	$R_{BE} = \infty$	9	V
$I_C$	Collector current		3	A
$P_C$	Collector dissipation	$T_c = 25^\circ\text{C}$	20	W
$T_J$	Junction temperature		175	$^\circ\text{C}$
$T_{stg}$	Storage temperature		-55 to 175	$^\circ\text{C}$
$R_{th-c}$	Thermal resistance	Junction to case	7.5	$^\circ\text{C/W}$

Note. Above parameters are guaranteed independently.

**ELECTRICAL CHARACTERISTICS** ( $T_c = 25^\circ\text{C}$ )

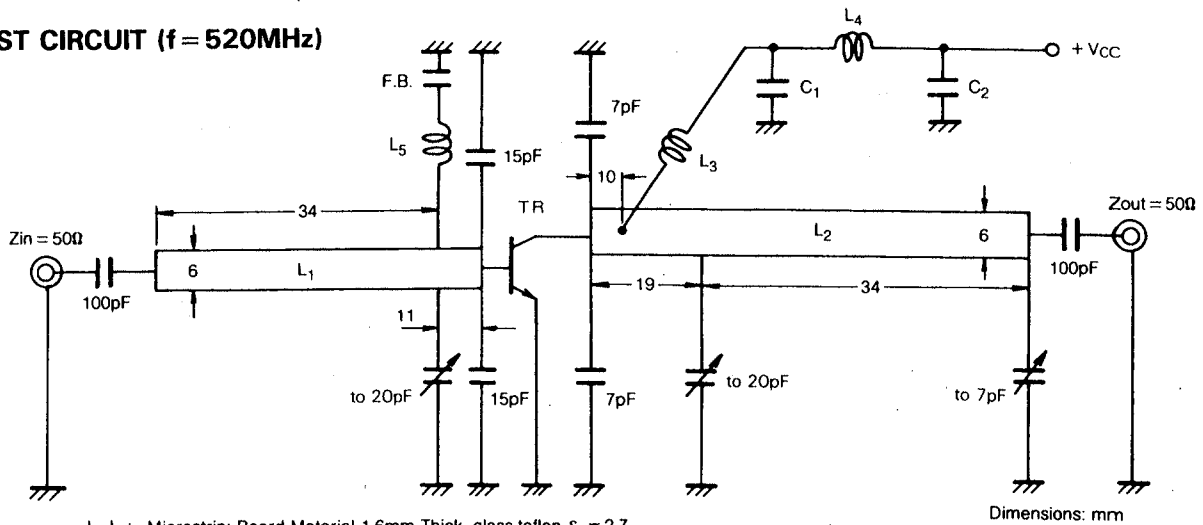
Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$V_{IBREBO}$	Emitter to base breakdown voltage	$I_E = 5\text{mA}$ , $I_C = 0$	3.5			V
$V_{IBRCBO}$	Collector to base breakdown voltage	$I_C = 10\text{mA}$ , $I_E = 0$	20			V
$V_{IBRICEO}$	Collector to emitter breakdown voltage	$I_C = 50\text{mA}$ , $R_{BE} = \infty$	9			V
$I_{CBO}$	Collector cut off current	$V_{CB} = 10\text{V}$ , $I_E = 0$			500	$\mu\text{A}$
$I_{EBO}$	Emitter cut off current	$V_{EB} = 2\text{V}$ , $I_C = 0$			500	$\mu\text{A}$
$h_{FE}$	DC forward current gain*	$V_{CE} = 5\text{V}$ , $I_C = 0.1\text{A}$	10	50	180	—
$P_O$	Power Output	$V_{CC} = 7.2\text{V}$ , $P_{in} = 2\text{W}$ , $f = 520\text{MHz}$	6	7		W
$\eta_C$	Collector efficiency		60	65		%

Note. \* Pulse test,  $P_W = 150\mu\text{s}$ , duty = 5%.

Above parameters, limits and conditions are subject to change.

**NPN EPITAXIAL PLANAR TYPE**

**TEST CIRCUIT (f = 520MHz)**

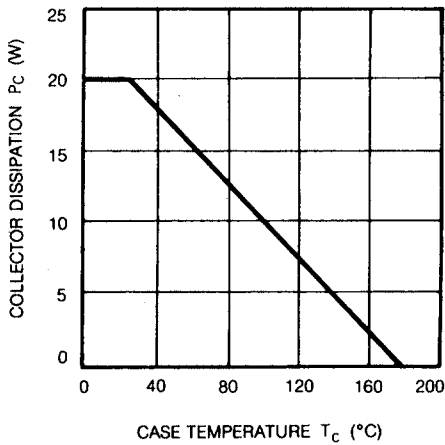


L<sub>1</sub>, L<sub>2</sub>: Microstrip: Board Material 1.6mm Thick, glass-tylon  $\epsilon_r = 2.7$   
 L<sub>3</sub>: 3 Turns AWG #20, 5mm I.D.  
 L<sub>4</sub>: 6 Turns AWG #20, 5mm I.D.  
 L<sub>5</sub>: 10 Turns AWG #26 Enameled Wire on 4mm O.D., 14mm Length Bakelite.

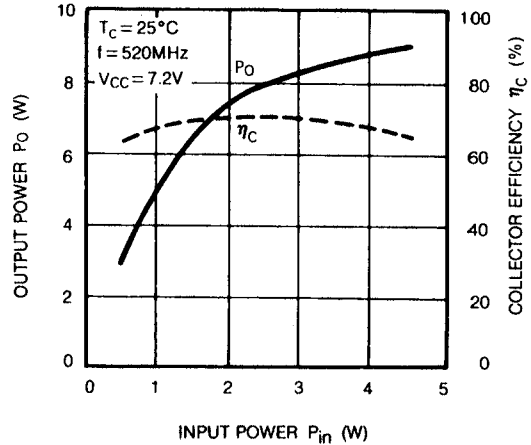
F.B.: Ferrite Bead  
 C<sub>1</sub>: 82pF, 220pF, 4700pF, 10 $\mu$ F in parallel.  
 C<sub>2</sub>: 82pF, 220pF, 10 $\mu$ F in parallel.

**TYPICAL PERFORMANCE DATA**

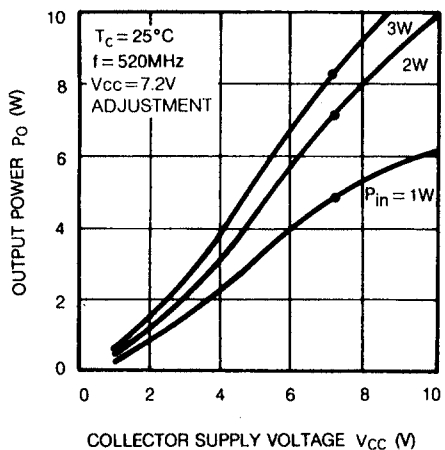
**COLLECTOR DISSIPATION VS. CASE TEMPERATURE**



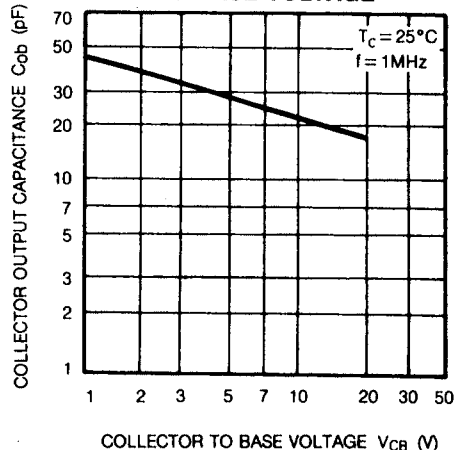
**OUTPUT POWER, COLLECTOR EFFICIENCY VS. INPUT POWER**



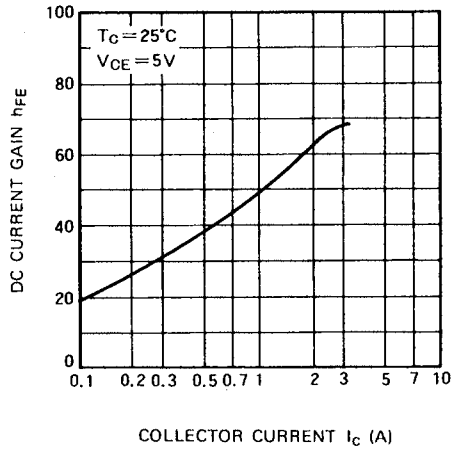
**OUTPUT POWER VS. COLLECTOR SUPPLY VOLTAGE**



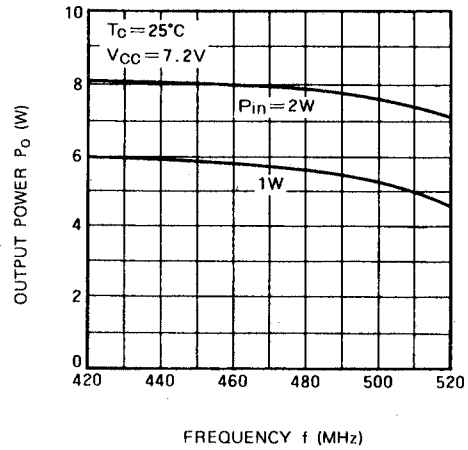
**COLLECTOR OUTPUT CAPACITANCE VS. COLLECTOR TO BASE VOLTAGE**



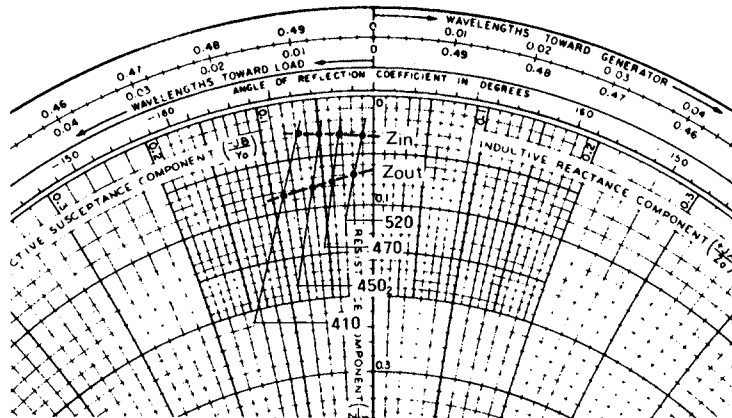
**DC CURRENT GAIN VS. COLLECTOR CURRENT**



**OUTPUT POWER VS. FREQUENCY**



**INPUT/OUTPUT IMPEDANCE**



f (MHz)	$Z_{in}(\Omega)$	$Z_{ot}(\Omega)$
410	1.4-j3.0	4.0-j4.4
450	1.4-j2.2	3.8-j3.0
470	1.5-j1.5	3.6-j2.0
520	1.6-j0.4	3.5-j1.0

$V_{CC} = 7.2\text{V}$ ,  $P_o = 6\text{W}$